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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Attn: OIPE

Makoto KOBAYASHI et al.

Application No.: 09/830,434

Docket No.: 109352

Filed: April 26, 2001

For: POLISHING PAD AND POLISHING METHOD FOR SEMICONDUCTOR WAFERS

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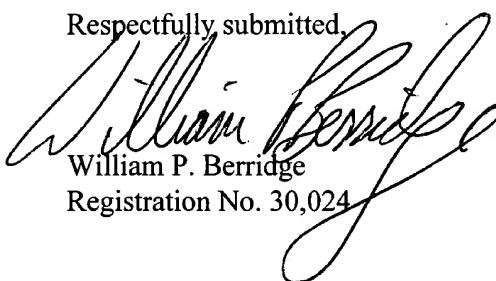
REQUEST FOR CORRECTION OF PALM RECORDS

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Sir:

Attached is a photocopy of the original filing receipt on which errors have been corrected in red. These errors are being brought to the attention of the Patent and Trademark Office so that it may correct its records.

Respectfully submitted,



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Date: November 20, 2001

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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE RECD	ATTY.DOCKET.NO	DRAWINGS	TOP CLAIMS	IND CLAIMS
09/830,434	04/26/2001	3723	1038	109352	3	9	10

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CONFIRMATION NO. 2453

FILING RECEIPT



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Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts" for this application, please submit any corrections to this Filing Receipt with your reply to the Notice. When the USPTO processes the reply to the Notice, the USPTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s)

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Domestic Priority data as claimed by applicant

Assignment For Published Patent Application
 Shin-Etsu Handotai Co., Ltd., Tokyo, Japan

THIS APPLICATION IS A 371 OF PCT/JP00/05595 08/21/2000

Foreign Applications

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Non-Publication Request: No

Early Publication Request: No

Title

I Polishing Pad and Polishing Method for Semiconductor Wafer
 Method and device for polishing semiconductor wafer.

Preliminary Class

Data entry by : NGUYEN, SON

T am : OIPE

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